

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A component lead comprising:
a lead finish comprising ~~between~~ from about 78% to less than and 80% by weight of lead, between about 9% and about 11% by weight of antimony, ~~between~~ greater than 5% and up to about 12% by weight of silver, and a balance of tin disposed over the component lead.
2. – 3. (Canceled)
4. (Currently Amended) The component lead of claim 1, wherein the component lead is to be coupled to a lead of a surface mount component.
5. (Currently Amended) The component lead of claim 1, wherein the component lead is coupled to a downhole electronic assembly.
6. (Currently Amended) A package structure comprising:
a package; and
a plurality of component leads coupled to a circuit included in the package and having a lead finish comprising ~~between~~ from about 78% to less than and 80% by weight of lead, between about 9% and about 11% by weight of antimony, ~~between~~ greater than 5% and up to about 12% by weight of silver, and a balance of tin.
7. (Withdrawn) The package structure of claim 6, wherein the circuit is included in a substrate.
8. (Withdrawn) The package structure of claim 7, wherein the package structure is part of a downhole electronic assembly.

9. (Currently Amended) A circuit board, comprising:
a processor; and
a circuit coupled to the processor and included in a package structure having a plurality component leads having a lead finish comprising ~~between~~ from about 78% to less than ~~and~~ 80% by weight of lead, between about 9% and about 11% by weight of antimony, ~~between~~ greater than 5% ~~and~~ up to about 12% by weight of silver, and a balance of tin.
10. (Withdrawn) The circuit board of claim 9, wherein the circuit includes a memory.
11. (Withdrawn) The circuit board of claim 9, wherein the circuit includes a digital-to-analog converter.
12. (Currently Amended) A system comprising:
a component lead having a lead finish disposed over the component lead, the ~~second~~ lead finish comprising ~~between~~ from about 78% to less than ~~and~~ 80% by weight of lead, between about 9% and about 11% by weight of antimony, ~~between~~ greater than 5% ~~and~~ up to about 12% by weight of silver, and a balance of tin; and
a downhole transducer coupled to the component lead.
13. (Canceled)
14. (Previously Presented) The system of claim 12, wherein the downhole transducer is selected from the group consisting of a downhole temperature indicator, a downhole vibration sensor, a pressure sensor, an accelerometer, and a fluxgate.
15. (Original) The system of claim 12, wherein the downhole transducer is to measure a subsurface characteristic that is selected from a group consisting of a downhole temperature, a downhole pressure, a resistivity of a subsurface formation, a porosity of a subsurface formation, a diameter of a borehole, and a shape of the borehole.

16. (Currently Amended) The system of claim 12, further comprising:
a processor coupled to the component lead.
17. (Currently Amended) The system of claim 12, further comprising:
an amplifier coupled to the component lead.
18. – 39. (Canceled).
40. (Currently Amended) An assembly comprising:
a downhole transducer coupled to a circuit trace included in a circuit attached to a composition including a first amount ~~between~~ from about 78% to less than and 80% by weight of lead, a second amount between about 9% and about 11% by weight of antimony, a third amount ~~between~~ greater than 5% ~~and up to~~ about 12% by weight of silver, and a balance of tin.
41. (Original) The assembly of claim 40, further comprising:
a processor to be communicatively coupled to the circuit.
42. (Original) The assembly of claim 40, wherein the circuit includes a data acquisition system.
43. (Original) The assembly of claim 40, wherein the circuit includes a filter.
44. – 46. (Canceled)